Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**BASE**

**EMITTER**



**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .004” x .004” min.**

**Backside Potential: COLLECTOR**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .015” X .015” DATE: 4/18/22**

**MFG: ZETEX THICKNESS .007” P/N: 2N2920**

**DG 10.1.2**

#### Rev B, 7/19/02